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**IDENTIFICATION OF APPLICATION**

Serial No.:	
Title: METHOD OF FORMING A CONDUCTIVE BARRIER LAYER HAVING IMPROVED ADHESION AND RESISTIVITY CHARACTERISTICS	
Applicant: MICHAEL FRIEDEMANN and VOLKER KAHLERT	Att'y/Agent: JMA
Client: AMD, INC.	File No.: 2000.106000/DE0247
Mailed: JUNE 24, 2003	Filed: Due Date: